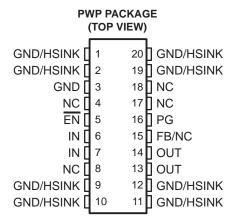
- 1 A Low-Dropout Voltage Regulator
- Available in 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V, 5.0-V Fixed Output and Adjustable Versions
- Dropout Voltage Down to 230 mV at 1 A (TPS76850)
- Ultra Low 85 µA Typical Quiescent Current
- Fast Transient Response
- 2% Tolerance Over Specified Conditions for Fixed-Output Versions
- Open Drain Power Good (See TPS767xx for Power-On Reset With 200-ms Delay Option)
- 8-Pin SOIC and 20-Pin TSSOP (PWP) Package
- Thermal Shutdown Protection

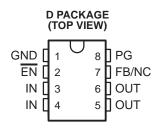
description

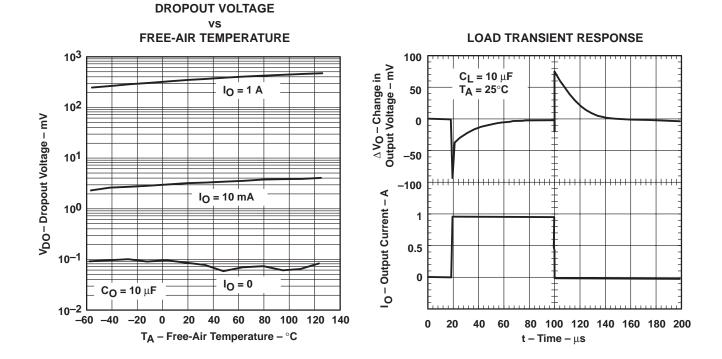
This device is designed to have a fast transient response and be stable with $10-\mu F$ low ESR capacitors. This combination provides high performance at a reasonable cost.

TPS76833



NC - No internal connection







Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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SLVS211B – JUNE 1999 – REVISED JULY

description (continued)

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 230 mV at an output current of 1 A for the TPS76850) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85 μ A over the full range of output current, 0 mA to 1 A). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to EN (enable) shuts down the regulator, reducing the quiescent current to less than 1 μ A at T_J = 25°C.

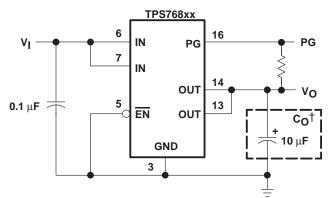
Power good (PG) is an active high output, which can be used to implement a power-on reset or a low-battery indicator.

The TPS768xx is offered in 1.5-V, 1.8-V, 2.5-V, 2.7-V, 2.8-V, 3.0-V, 3.3-V and 5.0-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.2 V to 5.5 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS768xx family is available in 8 pin SOIC and 20 pin PWP packages.

ТJ	OUTPUT VOLTAGE (V)	PACKAGED DEVICES			
-	ТҮР	TSSSOP (PWP)	SOIC (D)		
	5.0	TPS76850Q	TPS76850Q		
	3.3	TPS76833Q	TPS76833Q		
	3.0	TPS76830Q	TPS76830Q		
	2.8	TPS76828Q	TPS76828Q		
-40°C to 125°C	2.7	TPS76827Q	TPS76827Q		
	2.5	TPS76825Q	TPS76825Q		
	1.8	TPS76818Q	TPS76818Q		
	1.5	TPS76815Q	TPS76815Q		
	Adjustable 1.2 V to 5.5 V	TPS76801Q	TPS76801Q		

AVAILABLE OPTIONS

The TPS76801 is programmable using an external resistor divider (see application information). The D and PWP packages are available taped and reeled. Add an R suffix to the device type (e.g., TPS76801QDR).

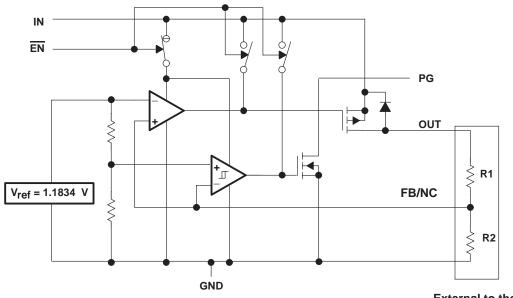


[†] See application information section for capacitor selection details.

Figure 1. Typical Application Configuration (For Fixed Output Options)

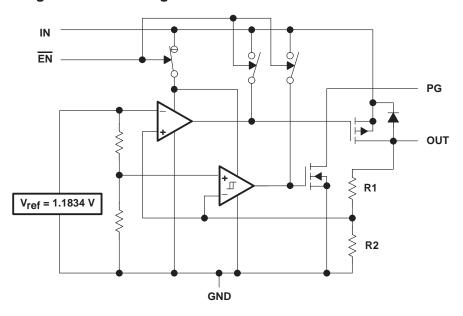


functional block diagram—adjustable version



External to the device

functional block diagram—fixed-voltage version





Terminal Functions – SOIC Package

TERMIN	IAL	1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
GND	1		Regulator ground
EN	2	I	Enable input
IN	3	I	Input voltage
IN	4	I	Input voltage
OUT	5	0	Regulated output voltage
OUT	6	0	Regulated output voltage
FB/NC	7	I	Feedback input voltage for adjustable device (no connect for fixed options)
PG	8	0	PG output

Terminal Functions – PWP Package

TERMINAL			DECODIDEION
NAME	NO.	1/0	DESCRIPTION
GND/HSINK	1		Ground/heatsink
GND/HSINK	2		Ground/heatsink
GND	3		LDO ground
NC	4		No connect
EN	5	I	Enable input
IN	6	1	Input
IN	7	I	Input
NC	8		No connect
GND/HSINK	9		Ground/heatsink
GND/HSINK	10		Ground/heatsink
GND/HSINK	11		Ground/heatsink
GND/HSINK	12		Ground/heatsink
OUT	13	0	Regulated output voltage
OUT	14	0	Regulated output voltage
FB/NC	15	I	Feedback input voltage for adjustable device (no connect for fixed options)
PG	16	0	PG output
NC	17		No connect
NC	18		No connect
GND/HSINK	19		Ground/heatsink
GND/HSINK	20		Ground/heatsink



SLVS211B - JUNE 1999 - REVISED JULY 1999

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage range [‡] , V _I Voltage range at EN Maximum PG voltage	–0.3 V to V _I + 0.3 V 16.5 V
Peak output current Continuous total power dissipation Output voltage, V _O (OUT, FB)	See dissipation rating tables
Operating virtual junction temperature range, T _J Storage temperature range, T _{stg} ESD rating, HBM	−40°C to 125°C −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ All voltage values are with respect to network terminal ground.

DISSIPATION RATING TABLE 1 – FREE-AIR TEMPERATURES

PACKAGE	AIR FLOW (CFM)	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
D	0	568.18 mW	5.6818 mW/°C	312.5 mW	227.27 mW
	250	904.15 mW	9.0415 mW/°C	497.28 mW	361.66 mW

DISSIPATION RATING TABLE 2 – FREE-AIR TEMPERATURES

PACKAGE	AIR FLOW (CFM)	T _A < 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING
PWP#	0	2.9 W	23.5 mW/°C	1.9 W	1.5 W
PVVP"	300	4.3 W	34.6 mW/°C	2.8 W	2.2 W
PWP	0	3 W	23.8 mW/°C	1.9 W	1.5 W
	300	7.2 W	57.9 mW/°C	4.6 W	3.8 W

[#] This parameter is measured with the recommended copper heat sink pattern on a 1-layer PCB, 5-in × 5-in PCB, 1 oz. copper, 2-in \times 2-in coverage (4 in²).

|| This parameter is measured with the recommended copper heat sink pattern on a 8-layer PCB, 1.5-in × 2-in PCB, 1 oz. copper with layers 1, 2, 4, 5, 7, and 8 at 5% coverage (0.9 in²) and layers 3 and 6 at 100% coverage (6 in²). For more information, refer to TI technical brief SLMA002.

recommended operating conditions

	MIN	MAX	UNIT
Input voltage, V _I ☆	2.7	10	V
Output voltage range, VO	1.2	5.5	V
Output current, IO (Note 1)	0	1.0	А
Operating virtual junction temperature, T _J (Note 1)	-40	125	°C

* To calculate the minimum input voltage for your maximum output current, use the following equation: VI(min) = VO(max) + VDO(max load). NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



electrical characteristics <u>ov</u>er recommended operating free-air $V_i = V_{O(typ)} + 1 V$, $I_O = 1 mA$, $\overline{EN} = 0 V$, $C_O = 10 \mu F$ (unless otherwise noted) temperature range,

	PARAMETER		TEST CC	NDITIONS	MIN	TYP	MAX	UNIT
		TD070004	$5.5 \text{ V} \ge \text{V}_{O} \ge 1.2 \text{ V},$	TJ = 25°C		Vo		
		TPS76801	5.5 V \ge V _O \ge 1.2 V,	$T_J = -40^{\circ}C$ to $125^{\circ}C$	0.98VO		1.02VO	
		TPS76815	TJ = 25°C,	2.7 V < V _{IN} < 10 V		1.5		
		1F370015	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	2.7 V < V _{IN} < 10 V	1.470		1.530	
		TPS76818	T _J = 25°C,	2.8 V < V _{IN} < 10 V		1.8		
		1F370010	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	2.8 V < V _{IN} < 10 V	1.764		1.836	
		TPS76825	TJ = 25°C,	3.5 V < V _{IN} < 10 V		2.5		
		11-370023	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	3.5 V < V _{IN} < 10 V	2.450		2.550	
Output vo	oltage 1 A load)	TPS76827	TJ = 25°C,	3.7 V < V _{IN} < 10 V		2.7		v
(see Note		11-370027	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	3.7 V < V _{IN} < 10 V	2.646		2.754	v
	,	TPS76828	$T_J = 25^{\circ}C$,	3.8 V < V _{IN} < 10 V		2.8		
		11 07 0020	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	3.8 V < V _{IN} < 10 V	2.744		2.856	
		TPS76830	TJ = 25°C,	4.0 V < V _{IN} < 10 V		3.0		
		11 07 0000	$T_J = -40^{\circ}C$ to $125^{\circ}C$,		2.940		3.060	
		TPS76833	$T_J = 25^{\circ}C$,	4.3 V < V _{IN} < 10 V		3.3		
		11 37 0033	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	4.3 V < V _{IN} < 10 V	3.234		3.366	
		TPS76850	TJ = 25°C,	6.0 V < V _{IN} < 10 V		5.0		
		11 87 8830	$T_J = -40^{\circ}C$ to $125^{\circ}C$,	6.0 V < V _{IN} < 10 V	4.900		5.100	
	nt current (GND current)		10 μA < I _O < 1 A,	•		85		μA
EN = 0V,	(see Note 2)		I _O = 1 A,	$T_J = -40^{\circ}C$ to $125^{\circ}C$			125	
	bltage line regulation (ΔV_0 es 2 and 3)	0/V0)	$V_{O} + 1 V < V_{I} \le 10 V,$	$T_J = 25^{\circ}C$		0.01		%/V
Load regu	ulation					3		mV
Output no	bise voltage		BW = 300 Hz to 50 kH C _O = 10 μF,	lz, TJ = 25°C		190		μVrm
Output cu	urrent Limit		V _O = 0 V			1.7	2	А
Thermal s	shutdown junction tempe	rature				150		°C
			EN = VI,	TJ = 25°C, 2.7 V < VJ < 10 V		1		μA
Standby of	current		EN = V _{I,}	T _J = -40°C to 125°C 2.7 V < V _I < 10 V			10	μA
FB input of	current	TPS76801	FB = 1.5 V		1	2		nA
	l enable input voltage	•			1.7			V
-	l enable input voltage						0.9	V
	pply ripple rejection (see	Note 2)	f = 1 KHz, TJ = 25°C	C _O = 10 μF,		60		dB
	Minimum input volta	ge for valid PG	I _{O(PG)} = 300μA		<u> </u>	1.1		V
	Trip threshold voltag	-	V _O decreasing		92		98	%Vo
PG	Hysteresis voltage					0.5		%Vo
	Output low voltage		Measured at V _O V _I = 2.7 V,	IO(PG) = 1mA	<u> </u>	0.15	0.4	V
			$V_{(PG)} = 5 V$	·U(PG) = 1117	<u> </u>	0.15	0.4	
	Leakage current		(-		μA
Input curr	rent (EN)		EN = 0 V EN = VI		-1	0	1	μA

NOTE: 2. Minimum IN operating voltage is 2.7 V or VO(typ) + 1 V, whichever is greater. Maximum IN voltage 10 V.



SLVS211B - JUNE 1999 - REVISED JULY 1999

electrical	characteristics	over	recommended	operating	free-air	temperature	range,
$V_i = V_{O(typ)}$) + 1 V, I _O = 1 mA,	EN = 0	V, C _O = 10 μF (u	nless otherw	ise noted)	(continued)	-

PARAMET	ED	TEST CONDITIONS		MIN	TYP	MAX	UNIT
FARAIVIET					IIF	IVIAA	UNIT
	TPS76828	I _O = 1 A,	$T_J = 25^{\circ}C$		500		
	1F 37 0020	I _O = 1 A,	$T_{J} = -40^{\circ}C \text{ to } 125^{\circ}C$			825	
	TPS76830	I _O = 1 A,	TJ = 25°C		450		mV
Dropout voltage	1F370030	I _O = 1 A,	$T_{J} = -40^{\circ}C \text{ to } 125^{\circ}C$			675	
(See Note 4)	TPS76833	I _O = 1 A,	T _J = 25°C		350		IIIV
	15370033	I _O = 1 A,	$T_{J} = -40^{\circ}C \text{ to } 125^{\circ}C$			575	
	LPS76850	I _O = 1 A,	TJ = 25°C		230		
		I _O = 1 A,	$T_{.1} = -40^{\circ}C$ to $125^{\circ}C$			380	

NOTES: 3. If $V_0 \le 1.8$ V then $V_{imax} = 10$ V, $V_{imin} = 2.7$ V:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{imax} - 2.7 V)}{100} \times 1000$$

If $V_O \ge 2.5$ V then $V_{imax} = 10$ V, $V_{imin} = V_O + 1$ V:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{imax} - (V_O + 1 V))}{100} \times 1000$$

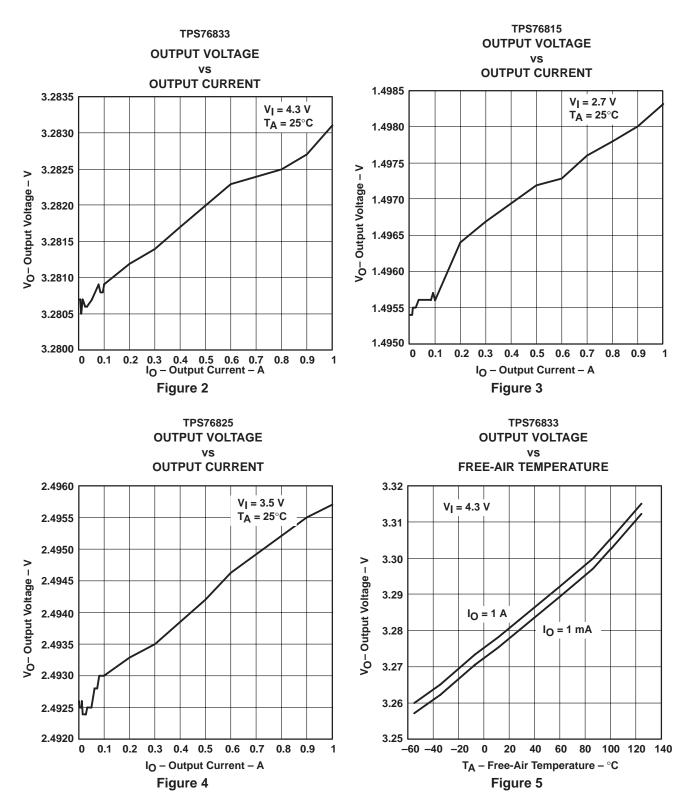
 IN voltage equals V_O(Typ) – 100 mV; TPS76801 output voltage set to 3.3 V nominal with external resistor divider. TPS76815, TPS76818, TPS76825, and TPS76827 dropout voltage limited by input voltage range limitations (i.e., TPS76830 input voltage needs to drop to 2.9 V for purpose of this test).

Table of Graphs

			FIGURE
	Output veltere	vs Output current	2, 3, 4
VO	Output voltage	vs Free-air temperature	5, 6, 7
	Ground current	vs Free-air temperature	8, 9
	Power supply ripple rejection	vs Frequency	10
	Output noise	vs Frequency	11
Z ₀	Output impedance	vs Frequency	12
V _{DO}	Dropout voltage	vs Free-air temperature	13
	Line transient response		14, 16
	Load transient response		15, 17
	Output voltage	vs Time	18
	Dropout voltage	vs Input voltage	19
	Equivalent series resistance (ESR)	vs Output current	21 – 24

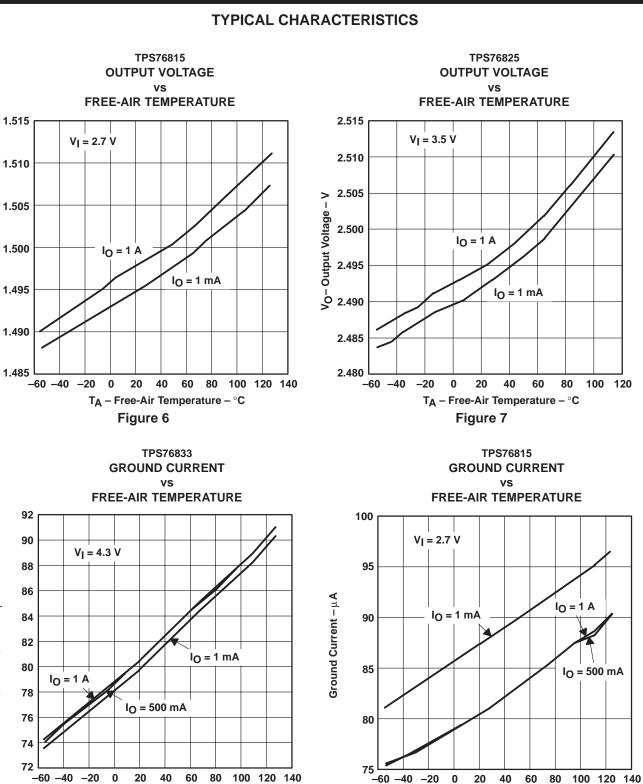


TYPICAL CHARACTERISTICS





SLVS211B - JUNE 1999 - REVISED JULY 1999



V_O- Output Voltage - V

Ground Current – μ A



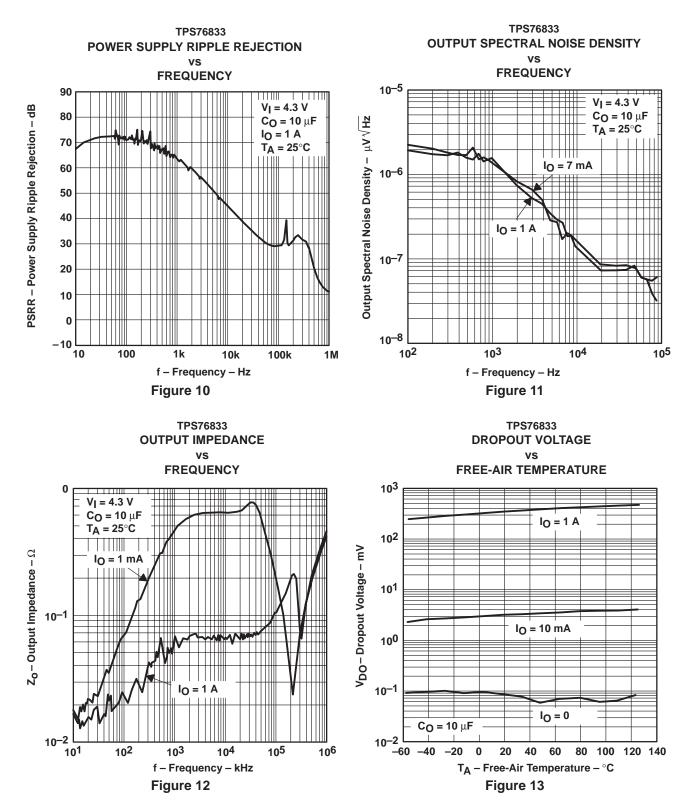
T_A – Free-Air Temperature – °C

Figure 8

T_A – Free-Air Temperature – °C

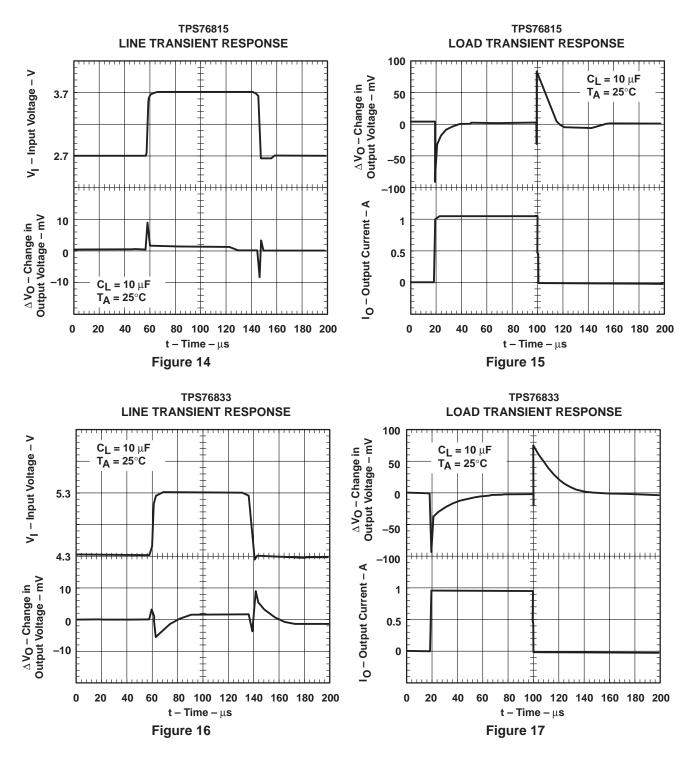
Figure 9

TYPICAL CHARACTERISTICS





TYPICAL CHARACTERISTICS





TYPICAL CHARACTERISTICS

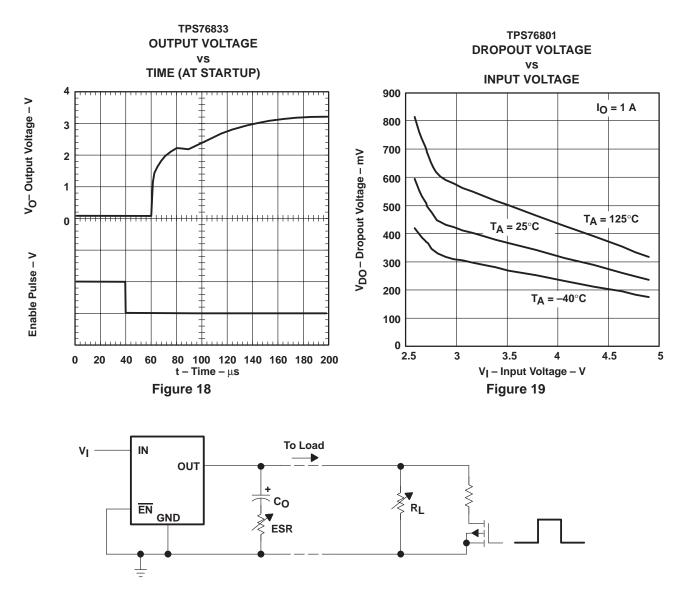
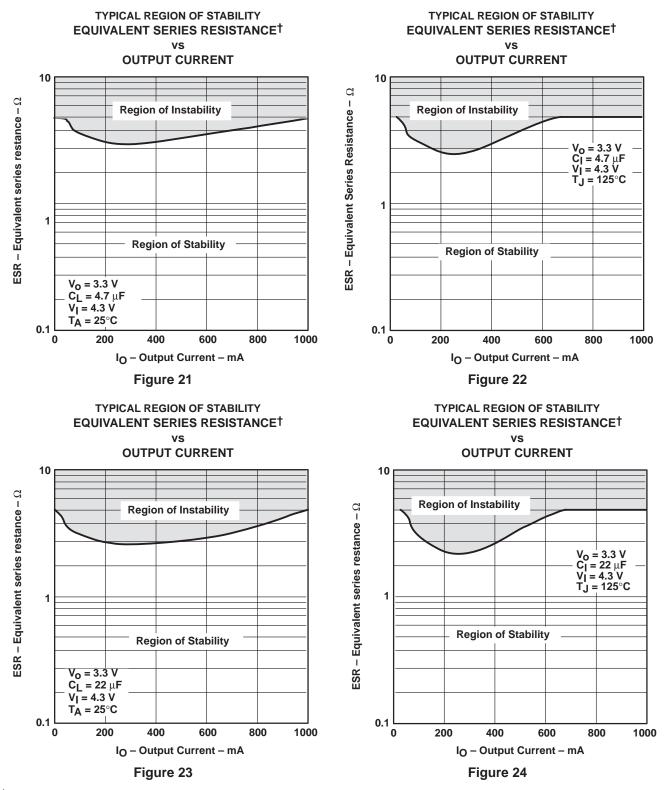


Figure 20. Test Circuit for Typical Regions of Stability (Figures 21 through 24) (Fixed Output Options)

[†] Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C_O.



SLVS211B - JUNE 1999 - REVISED JULY 1999



TYPICAL CHARACTERISTICS

† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to CO.



SLVS211B - JUNE 1999 - REVISED JULY 1999

APPLICATION INFORMATION

The TPS768xx family includes eight fixed-output voltage regulators (1.5 V, 1.8 V, 2.5 V, 2.7 V, 2.8 V, 3.0 V, 3.3 V, and 5.0 V), and offers an adjustable device, the TPS76801 (adjustable from 1.2 V to 5.5 V).

device operation

The TPS768xx features very low quiescent current, which remains virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). The TPS768xx uses a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range.

Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS768xx quiescent current remains low even when the regulator drops out, eliminating both problems.

The TPS768xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces guiescent current to 2 µA. If the shutdown feature is not used, EN should be tied to ground. Response to an enable transition is quick; regulated output voltage is reestablished in typically 120 μ s.

minimum load requirements

The TPS768xx family is stable even at zero load; no minimum load is required for operation.

FB - pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option. The output voltage is sensed through a resistor divider network to close the loop as it is shown in Figure 26. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential.

external capacitor requirements

An input capacitor is not usually required; however, a ceramic bypass capacitor (0.047 µF or larger) improves load transient response and noise rejection if the TPS768xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS768xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 µF and the ESR (equivalent series resistance) must be between 50 m Ω and 1.5 Ω . Capacitor values 10 μ F or larger are acceptable, provided the ESR is less than 1.5 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 10 µF surface-mount ceramic capacitors, including devices from Sprague and Kemet, meet the ESR requirements stated above.



APPLICATION INFORMATION

external capacitor requirements (continued)

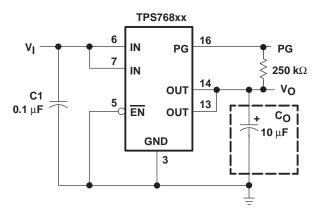


Figure 25. Typical Application Circuit (Fixed Versions)

programming the TPS76801 adjustable LDO regulator

The output voltage of the TPS76801 adjustable regulator is programmed using an external resistor divider as shown in Figure 26. The output voltage is calculated using:

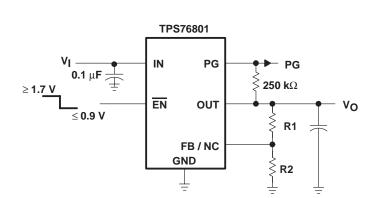
$$V_{O} = V_{ref} \times \left(1 + \frac{R_1}{R_2}\right)$$
(1)

Where

 $V_{ref} = 1.1834 V typ$ (the internal reference voltage)

 $R1 = \left(\frac{V_O}{V_{ref}} - 1\right) \times R2$

Resistors R1 and R2 should be chosen for approximately 50- μ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 30.1 k Ω to set the divider current at 50 μ A and then calculate R1 using:



OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	UNIT
2.5 V	33.2	30.1	kΩ
3.3 V	53.6	30.1	kΩ
3.6 V	61.9	30.1	kΩ
4.75 V	90.8	30.1	kΩ

Figure 26. TPS76801 Adjustable LDO Regulator Programming



(2)

APPLICATION INFORMATION

power-good indicator

The TPS768xx features a power-good (PG) output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to between 92% and 98% of its nominal regulated value, the PG output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. PG can be used to drive power-on reset circuitry or used as a low-battery indicator. PG does not assert itself when the regulated output voltage falls out of the specified 2% tolerance, but instead reports an output voltage low, relative to its nominal regulated value.

regulator protection

The TPS768xx PMOS-pass transistor has a built-in back diode that conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS768xx also features internal current limiting and thermal protection. During normal operation, the TPS768xx limits output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125°C; the maximum junction temperature should be restricted to 125°C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, PD(max), and the actual dissipation, PD, which must be less than or equal to P_{D(max)}.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

Where

T_{.1}max is the maximum allowable junction temperature

 $R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 172°C/W for the 8-terminal SOIC and 32.6°C/W for the 20-terminal PWP with no airflow.

T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$\mathsf{P}_{\mathsf{D}} = \left(\mathsf{V}_{\mathsf{I}} - \mathsf{V}_{\mathsf{O}}\right) \times \mathsf{I}_{\mathsf{O}}$$

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

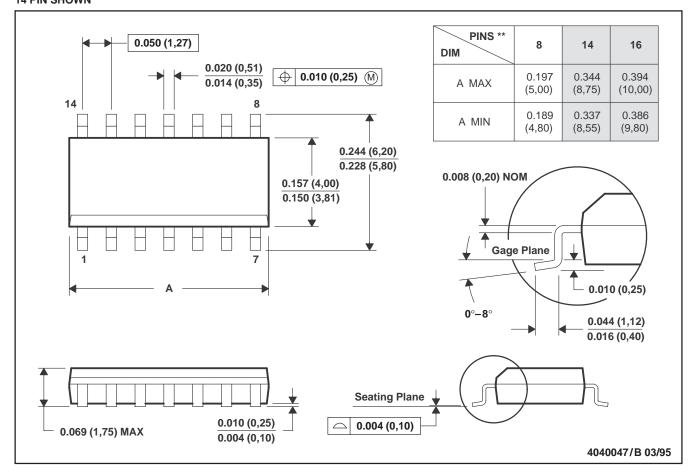


SLVS211B - JUNE 1999 - REVISED JULY 1999

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

D (R-PDSO-G**) **14 PIN SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Four center pins are connected to die mount pad.
- E. Falls within JEDEC MS-012



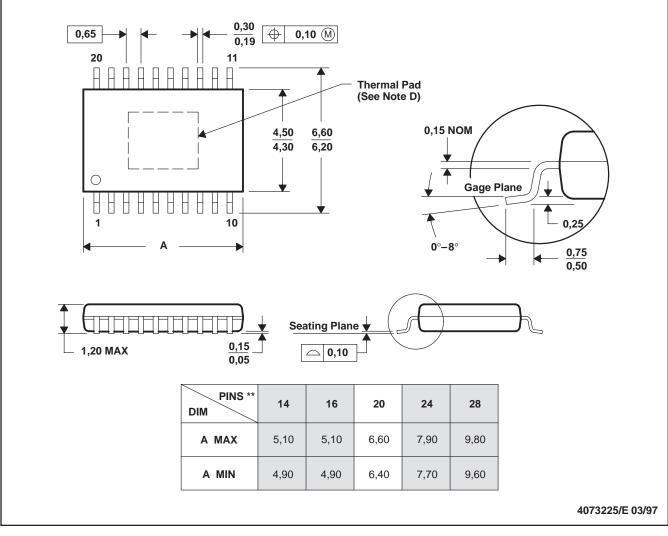
SLVS211B – JUNE 1999 – REVISED JULY 1999

MECHANICAL DATA

PWP (R-PDSO-G**)

PowerPAD[™] PLASTIC SMALL-OUTLINE PACKAGE

20-PIN SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusions.

D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.

E. Falls within JEDEC MO-153

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